# 504105624 11/21/2016

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
BOK ENG CHEAH	11/17/2016
MIN SUET LIM	11/17/2016
JACKSON CHUNG PENG KONG	11/17/2016

### **RECEIVING PARTY DATA**

Name:	INTEL CORPORATION	
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City:	SANTA CLARA	
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### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	15354291

### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER: 884.Y07US1

NAME OF SUBMITTER: NANCY CUNDALL

SIGNATURE: /Nancy Cundall/

DATE SIGNED: 11/21/2016

**Total Attachments: 3** 

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PATENT 504105624 REEL: 040393 FRAME: 0374

# RECORDATION FORM COVER SHEET PATENTS ONLY

Atty Ref/Docket No.: 884.Y07US1 Patent and Trademark Office To the Director of the U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof. Name and address of receiving party(ies): 1. Name of conveying party(ies): Name: Intel Corporation Bok Eng Cheah, Min Suet Lim, Jackson Chung Peng Street Address: 2200 Mission College Blvd. Kong Additional name(s) of conveying party(ies) attached? City: Santa Clara State: CA Zip: 95054 Country: United States of America [ ]Yes [X]No Additional name(s) & address(es) attached? [ ]Yes 3. Nature of conveyance: XNo [X] Assignment [ ] Merger [ ] Security Agreement [ ] Change of Name [ ] Other Execution Date: November 17, 2016, November 17, 2016, November 17, 2016 4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: A. Patent Application No.(s) B. Patent No.(s) Serial No. 15/354,291 Additional numbers attached? [ ]Yes [X]No 6. Total number of applications and patents involved: 1 5. Name and address of party to whom correspondence 7. Total fee (37 CFR 3.41):\$ 0.00 concerning document should be mailed: Name: Michael L. Lynch [[Enclosed [Authorized to be charged to deposit account Address: 504238 Schwegman Lundberg & Woessner, P.A. P.O. Box 2938 8. Please charge any additional fees or credit any over Minneapolis, MN 55402--0938 payments to our Deposit Account No.: 504238 DO NOT USE THIS SPACE Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Michael L. Lynch |
Signature Michael L. Lynch/Reg. No. 30,871 Name of Person Signing Total number of pages including cover sheet: 3

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Intel Docket No.: P107946 SLW Reference No.: 884.Y07US1

# <u>ASSIGNMENT</u>

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

# <Bok Eng Cheah, Min Suet Lim, Jackson Chung Peng Kong>

hereby sell, assign, and transfer to:

# Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

### MICROELECTRONIC DEVICE PACKAGE HAVING ALTERNATELY STACKED DIE

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)			
	which was filed on November 17, 2016 as		
	United States of America Application Number 15/354,291 Country or International Office		

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and tegal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors.

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assigns, and logal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or logal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and logal representatives; and

covenant with said Assignce, its successors, assigns, and legal representatives that no assignment, grant, mortgage. license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Bok Eng Cheah Date Signed

| 17 | Nov 2016 |
| Jacksop Chung Peng Kong Date Signed |

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**RECORDED: 11/21/2016**